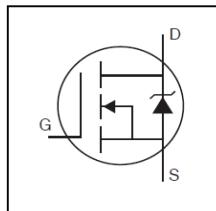


**Features**

- Advanced Process Technology
- Ultra Low On-Resistance
- Logic Level Gate Drive
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to  $T_{jmax}$
- Lead-Free, RoHS Compliant
- Automotive Qualified \*



HEXFET® Power MOSFET

$V_{DSS}$	40V
$R_{DS(on)}$ typ.	1.0mΩ
	1.4mΩ
$I_D$ (Silicon Limited)	380A①
$I_D$ (Package Limited)	240A



G	D	S
Gate	Drain	Source

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRLS3034-7P	D <sup>2</sup> Pak 7 Pin	Tube	50	AUIRLS3034-7P
		Tape and Reel Left	800	AUIRLS3034-7TRL

**Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (TA) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.	Units
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	380①	A
$I_D$ @ $T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	270①	
$I_D$ @ $T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Package Limited)	240	
$I_{DM}$	Pulsed Drain Current ②	1540	
$P_D$ @ $T_C = 25^\circ\text{C}$	Maximum Power Dissipation	380	W
	Linear Derating Factor	2.5	$\text{W}/^\circ\text{C}$
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy (Thermally Limited) ③	250	$\text{mJ}$
$I_{AR}$	Avalanche Current ②	See Fig.14,15, 22a, 22b	A
$E_{AR}$	Repetitive Avalanche Energy ②		$\text{mJ}$
$dv/dt$	Peak Diode Recovery ④	1.3	$\text{V}/\text{ns}$
$T_J$	Operating Junction and	-55 to + 175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

**Thermal Resistance**

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ⑨⑩	—	0.40	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient ⑧	—	40	

HEXFET® is a registered trademark of Infineon.

 \*Qualification standards can be found at [www.infineon.com](http://www.infineon.com)

**Static @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

Parameter		Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{\text{GS}} = 0\text{V}$ , $I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.035	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = 5\text{mA}$ ②
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	1.0	1.4	$\text{m}\Omega$	$V_{\text{GS}} = 10\text{V}$ , $I_D = 200\text{A}$ ⑤
		—	1.2	1.7		$V_{\text{GS}} = 4.5\text{V}$ , $I_D = 180\text{A}$ ⑤
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	1.0	—	2.5	V	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250\mu\text{A}$
$g_{\text{fs}}$	Forward Trans conductance	370	—	—	S	$V_{\text{DS}} = 10\text{V}$ , $I_D = 220\text{A}$
$R_G$	Gate Resistance	—	1.9	—	$\Omega$	
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	—	—	20	$\mu\text{A}$	$V_{\text{DS}} = 40\text{V}$ , $V_{\text{GS}} = 0\text{V}$
		—	—	250		$V_{\text{DS}} = 40\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_J = 125^\circ\text{C}$
$I_{\text{GSS}}$	Gate-to-Source Forward Leakage	—	—	100	$\text{nA}$	$V_{\text{GS}} = 20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{\text{GS}} = -20\text{V}$

**Dynamic Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

$Q_g$	Total Gate Charge	—	120	180	nC	$I_D = 170\text{A}$ $V_{\text{DS}} = 20\text{V}$ $V_{\text{GS}} = 4.5\text{V}$ ⑤
$Q_{\text{gs}}$	Gate-to-Source Charge	—	32	—		
$Q_{\text{gd}}$	Gate-to-Drain Charge	—	71	—		
$Q_{\text{sync}}$	Total Gate Charge Sync. ( $Q_g - Q_{\text{gd}}$ )	—	49	—		
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	71	—	ns	$V_{\text{DD}} = 26\text{V}$ $I_D = 220\text{A}$ $R_G = 2.7\Omega$ $V_{\text{GS}} = 4.5\text{V}$ ⑤
$t_r$	Rise Time	—	590	—		
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	94	—		
$t_f$	Fall Time	—	200	—		
$C_{\text{iss}}$	Input Capacitance	—	10990	—	pF	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 40\text{V}$ $f = 1.0\text{MHz}$
$C_{\text{oss}}$	Output Capacitance	—	2030	—		
$C_{\text{rss}}$	Reverse Transfer Capacitance	—	1100	—		
$C_{\text{oss eff. (ER)}}$	Effective Output Capacitance (Energy Related)	—	2520	—		$V_{\text{GS}} = 0\text{V}$ , $V_{\text{DS}} = 0\text{V}$ to $32\text{V}$ ⑦
$C_{\text{oss eff. (TR)}}$	Effective Output Capacitance (Time Related)	—	3060	—		$V_{\text{GS}} = 0\text{V}$ , $V_{\text{DS}} = 0\text{V}$ to $32\text{V}$ ⑥

**Diode Characteristics**

Parameter		Min.	Typ.	Max.	Units	Conditions
$I_s$	Continuous Source Current (Body Diode)	—	—	380 ①	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{\text{SM}}$	Pulsed Source Current (Body Diode) ②	—	—	1540		
$V_{\text{SD}}$	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}$ , $I_s = 200\text{A}$ , $V_{\text{GS}} = 0\text{V}$ ⑤
$t_{\text{rr}}$	Reverse Recovery Time	—	46	—	ns	$T_J = 25^\circ\text{C}$ $V_{\text{DD}} = 34\text{V}$
		—	49	—		$T_J = 125^\circ\text{C}$ $I_F = 220\text{A}$ ,
$Q_{\text{rr}}$	Reverse Recovery Charge	—	100	—	nC	$T_J = 25^\circ\text{C}$ $di/dt = 100\text{A}/\mu\text{s}$ ⑤
		—	110	—		$T_J = 125^\circ\text{C}$
$I_{\text{RRM}}$	Reverse Recovery Current	—	3.7	—	A	$T_J = 25^\circ\text{C}$
$t_{\text{on}}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_s + L_D$ )				

**Notes:**

- ① Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 240A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ Limited by  $T_{\text{Jmax}}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.010\text{mH}$ ,  $R_G = 25\Omega$ ,  $I_{\text{AS}} = 220\text{A}$ ,  $V_{\text{GS}} = 10\text{V}$ . Part not recommended for use above this value.
- ④  $I_{\text{SD}} \leq 220\text{A}$ ,  $di/dt \leq 1240\text{A}/\mu\text{s}$ ,  $V_{\text{DD}} \leq V_{(\text{BR})\text{DSS}}$ ,  $T_J \leq 175^\circ\text{C}$ .
- ⑤ Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ⑥  $C_{\text{oss eff. (TR)}}$  is a fixed capacitance that gives the same charging time as  $C_{\text{oss}}$  while  $V_{\text{DS}}$  is rising from 0 to 80%  $V_{\text{DSS}}$ .
- ⑦  $C_{\text{oss eff. (ER)}}$  is a fixed capacitance that gives the same energy as  $C_{\text{oss}}$  while  $V_{\text{DS}}$  is rising from 0 to 80%  $V_{\text{DSS}}$ .
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994
- ⑨  $R_\theta$  is measured at  $T_J$  approximately  $90^\circ\text{C}$ .
- ⑩  $R_{\theta\text{JC}}$  value shown is at time zero

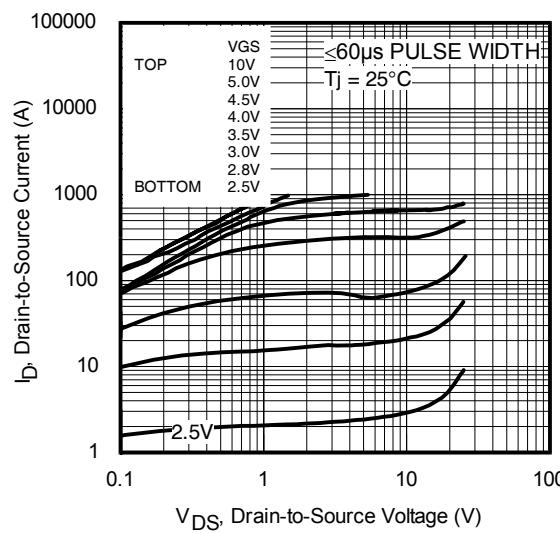


Fig. 1 Typical Output Characteristics

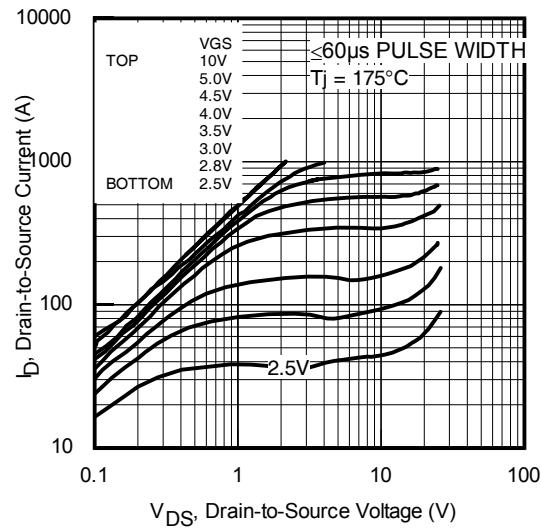


Fig. 2 Typical Output Characteristics

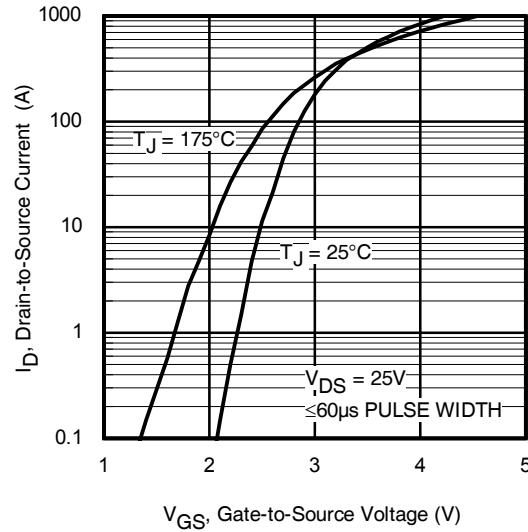


Fig. 3 Typical Transfer Characteristics

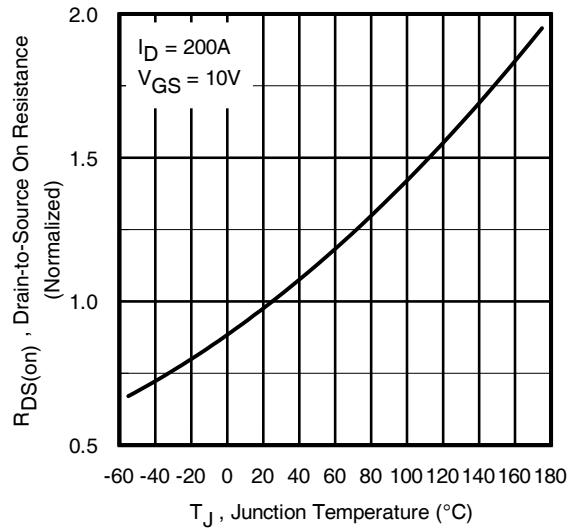


Fig. 4 Normalized On-Resistance vs. Temperature

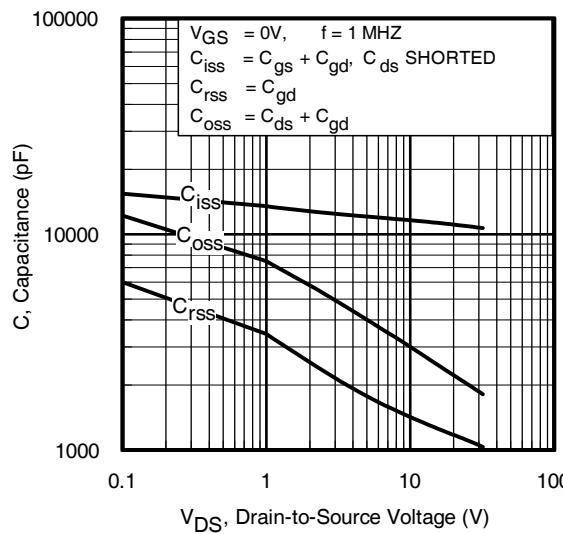


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

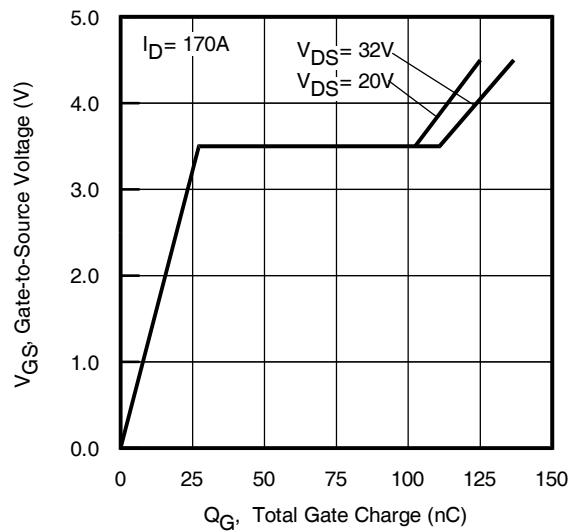


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

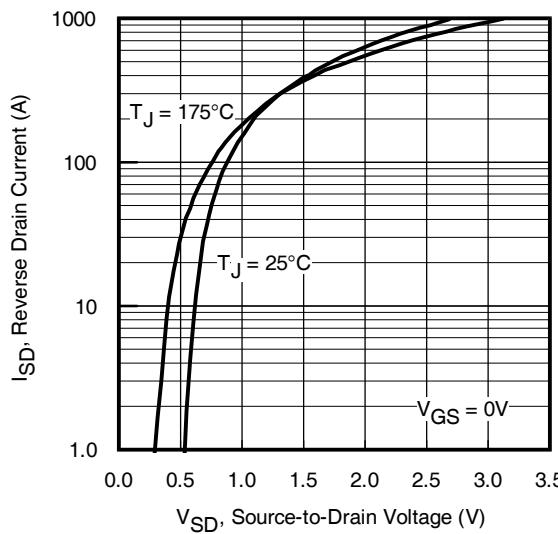


Fig. 7 Typical Source-to-Drain Diode

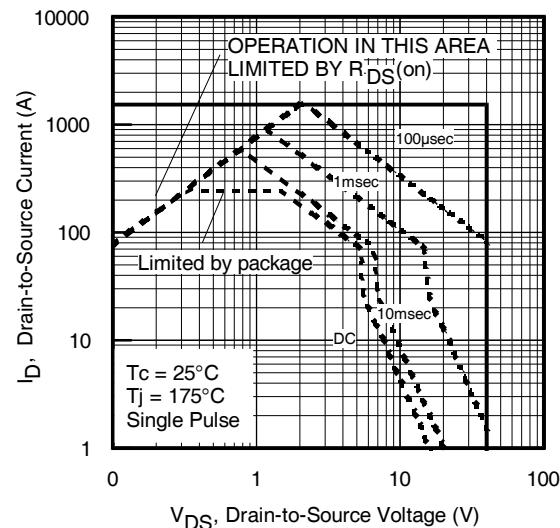


Fig 8. Maximum Safe Operating Area

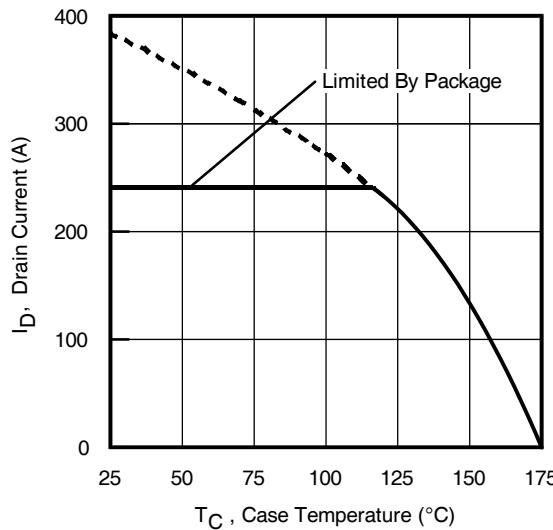


Fig 9. Maximum Drain Current vs. Case Temperature

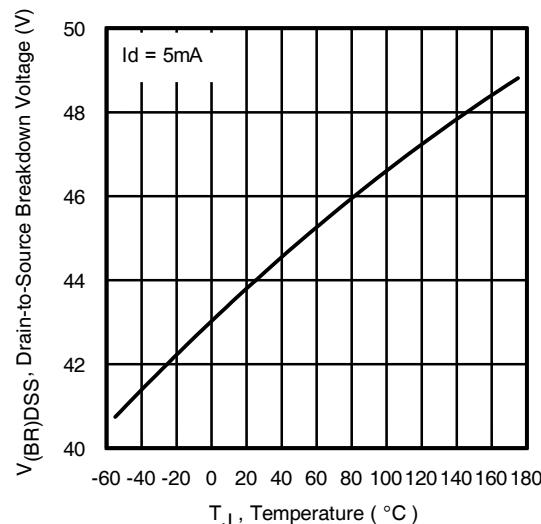


Fig 10. Drain-to-Source Breakdown Voltage

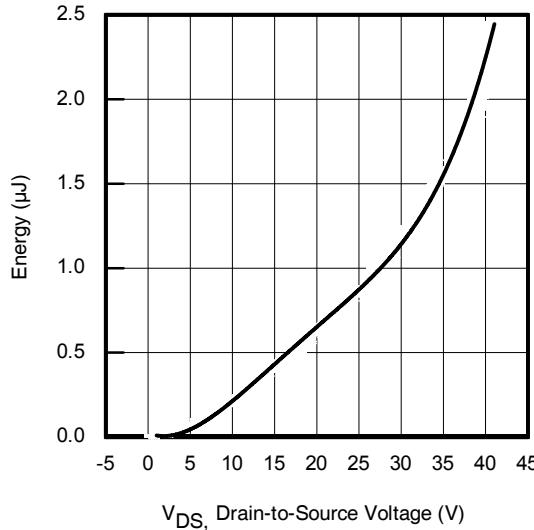


Fig 11. Typical Coss Stored Energy

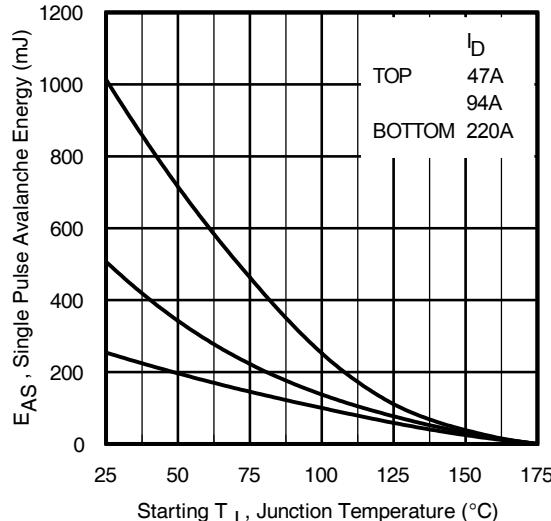


Fig 12. Maximum Avalanche Energy vs. Drain Current

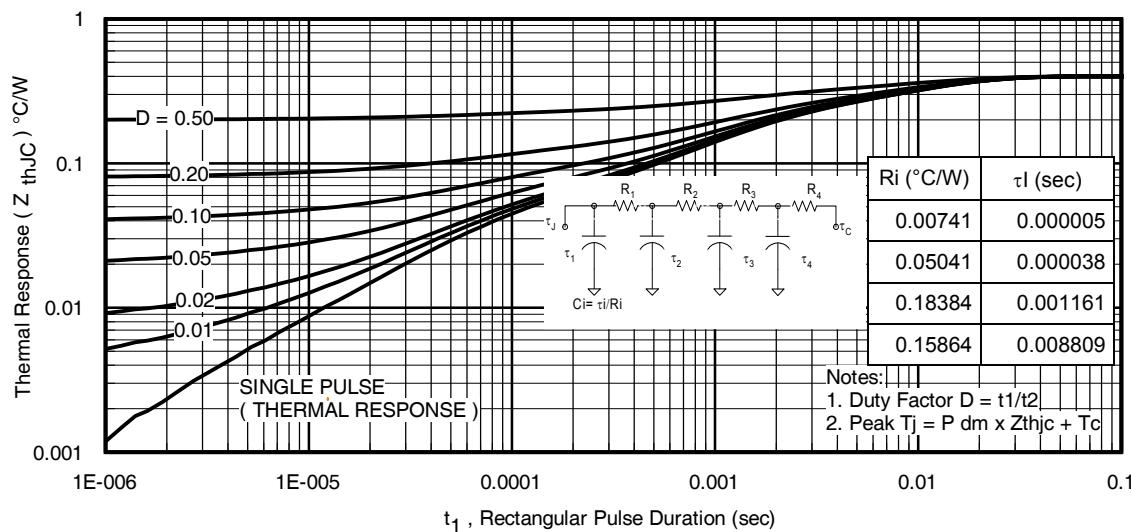


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

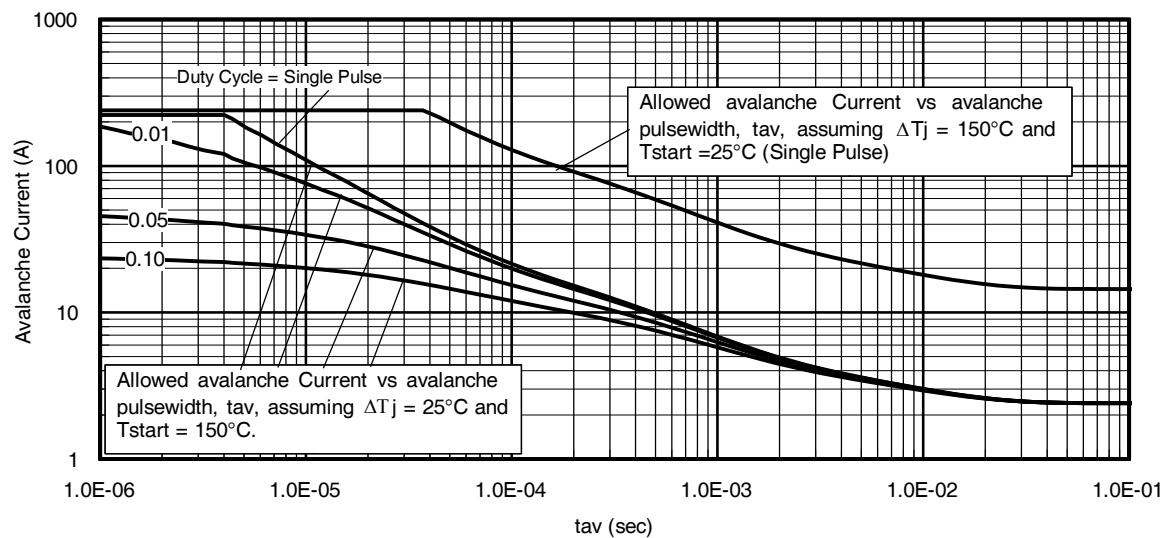


Fig 14. Avalanche Current vs. Pulse width

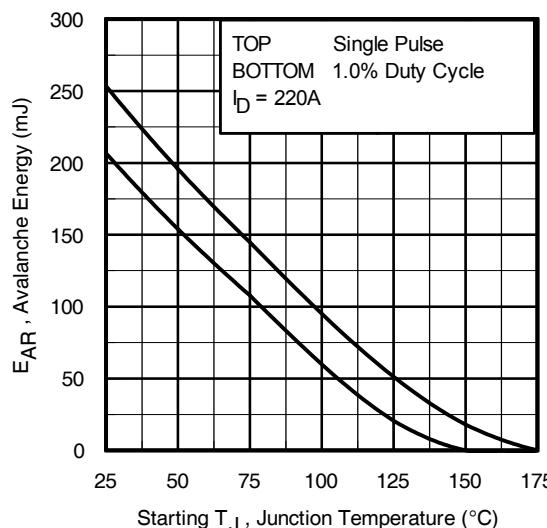


Fig 15. Maximum Avalanche Energy vs. Temperature

**Notes on Repetitive Avalanche Curves , Figures 14, 15:  
(For further info, see AN-1005 at [www.infineon.com](http://www.infineon.com))**

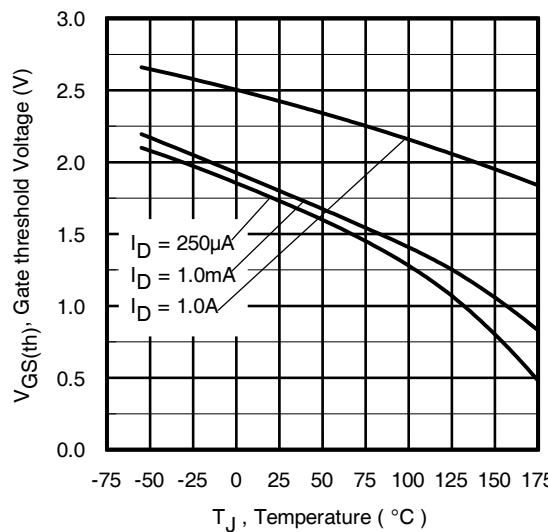
1. Avalanche failures assumption:  
Purely a thermal phenomenon and failure occurs at a temperature far in excess of  $T_{jmax}$ . This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as  $T_{jmax}$  is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 22a, 22b.
4.  $P_D(\text{ave})$  = Average power dissipation per single avalanche pulse.
5.  $BV$  = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6.  $I_{av}$  = Allowable avalanche current.
7.  $\Delta T$  = Allowable rise in junction temperature, not to exceed  $T_{jmax}$  (assumed as 25°C in Figure 13, 14).

$t_{av}$  = Average time in avalanche.  
 $D$  = Duty cycle in avalanche =  $t_{av}/f$   
 $Z_{thJC}(D, t_{av})$  = Transient thermal resistance, see Figures 13)

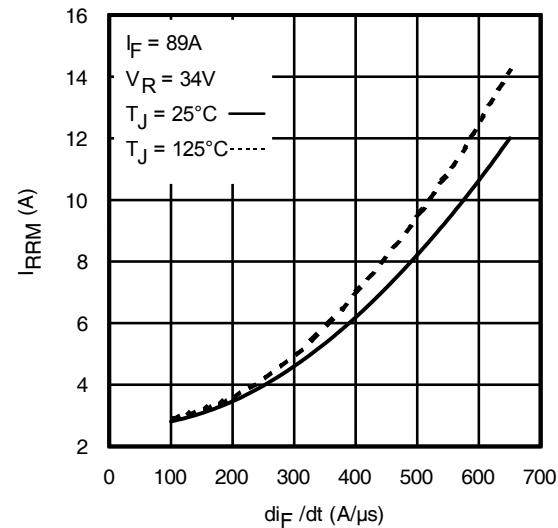
$$P_{D(\text{ave})} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

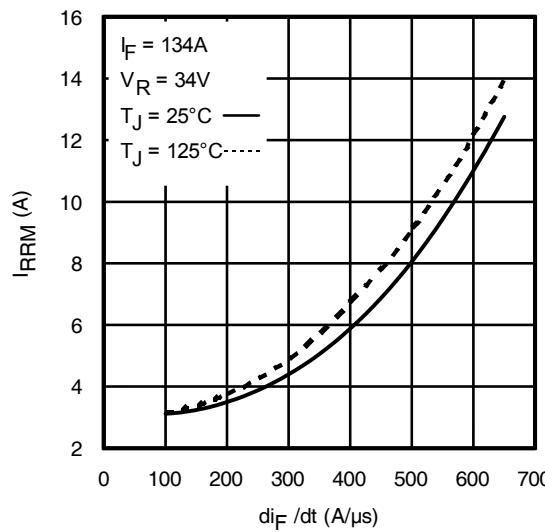
$$E_{AS(AR)} = P_{D(\text{ave})} \cdot t_{av}$$



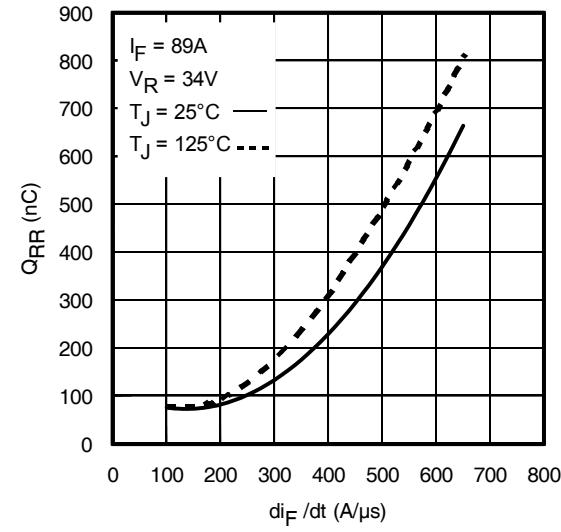
**Fig. 16.** Threshold Voltage vs. Temperature



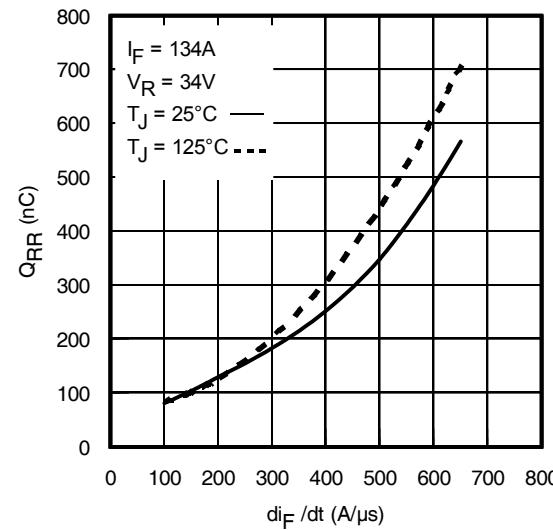
**Fig. 17 -** Typical Recovery Current vs.  $di_F/dt$



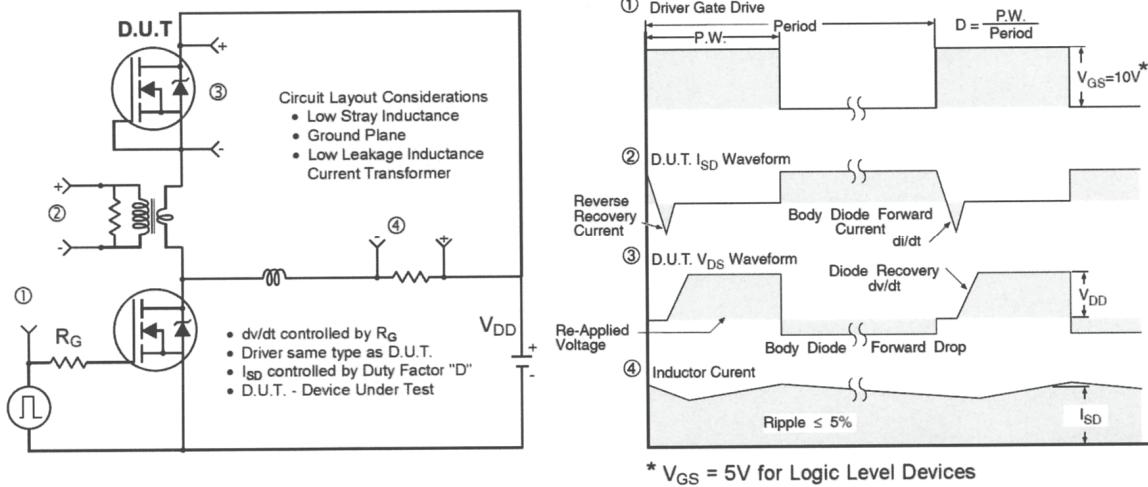
**Fig. 18 -** Typical Recovery Current vs.  $di_F/dt$



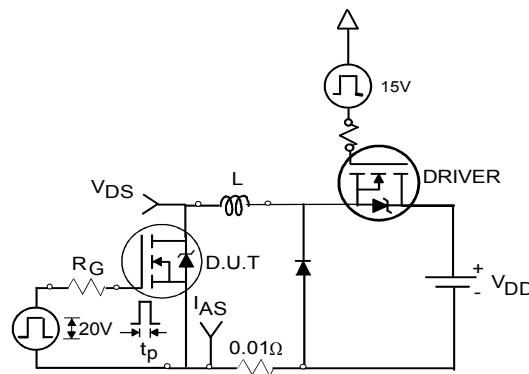
**Fig. 19 -** Typical Stored Charge vs.  $di_F/dt$



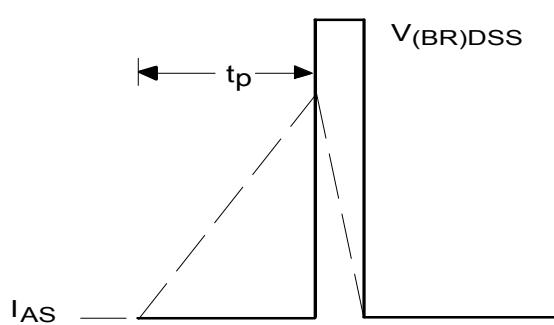
**Fig. 20 -** Typical Stored Charge vs.  $di_F/dt$



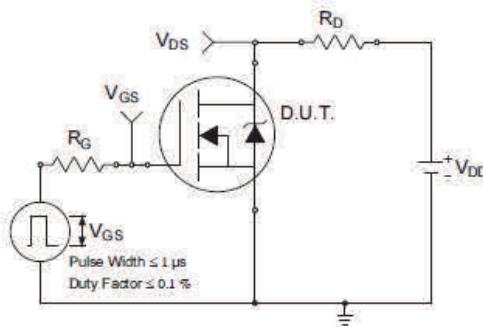
**Fig 21.** Peak Diode Recovery  $dv/dt$  Test Circuit for N-Channel HEXFET® Power MOSFETs



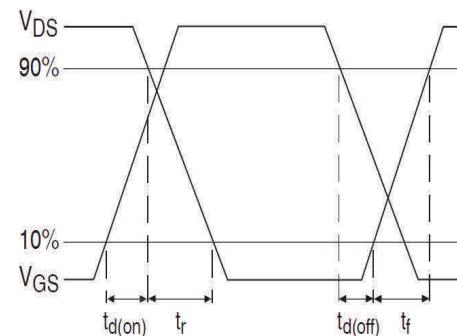
**Fig 22a.** Unclamped Inductive Test Circuit



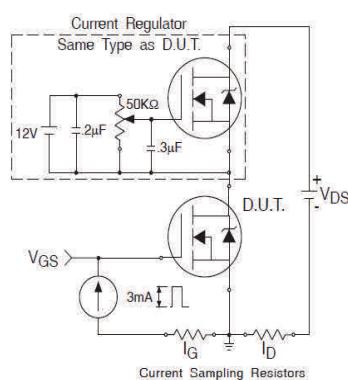
**Fig 22b.** Unclamped Inductive Waveforms



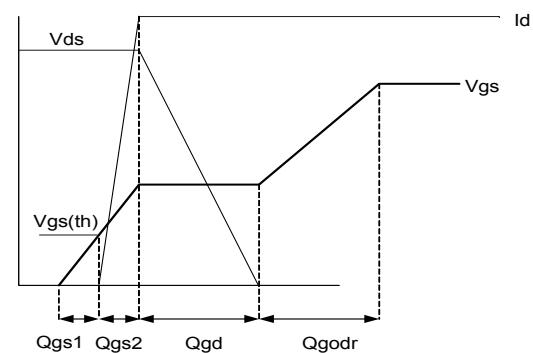
**Fig 23a.** Switching Time Test Circuit



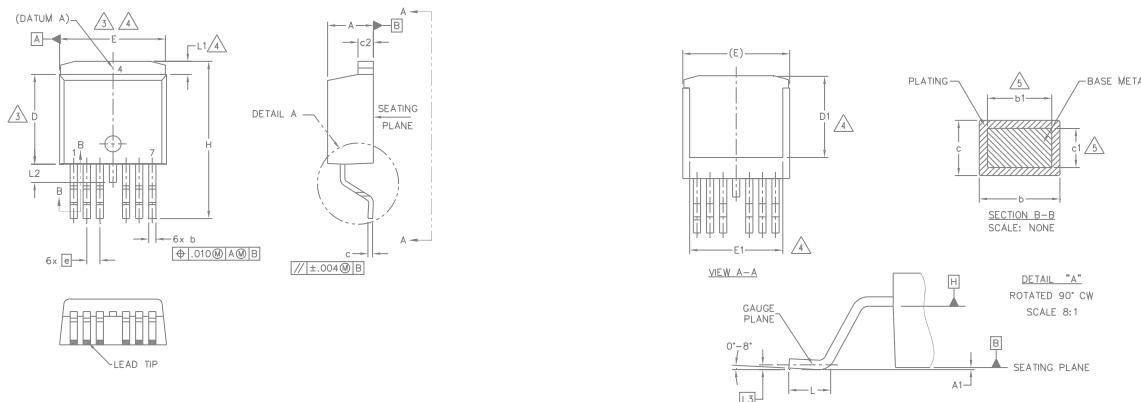
**Fig 23b.** Switching Time Waveforms



**Fig 24a.** Gate Charge Test Circuit



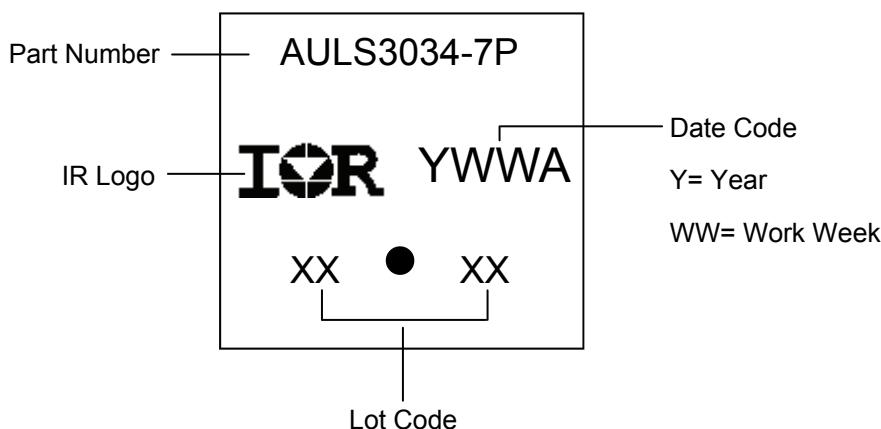
**Fig 24b.** Gate Charge Waveform

D<sup>2</sup>Pak - 7 Pin Package Outline (Dimensions are shown in millimeters (inches))

S Y M B O L	DIMENSIONS				N O T E S	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	4.06	4.83	.160	.190		
A1	—	0.254	—	.010		
b	0.51	0.99	.020	.036	5	
b1	0.51	0.89	.020	.032		
c	0.38	0.74	.015	.029		
c1	0.38	0.58	.015	.023		
c2	1.14	1.65	.045	.065		
D	8.38	9.65	.330	.380	3	
D1	6.86	7.42	.270	.292	4	
E	9.65	10.54	.380	.415	3,4	
E1	6.22	8.48	.245	.334	4	
e	1.27 BSC		.050 BSC			
H	14.61	15.88	.575	.625		
L	1.78	2.79	.070	.110		
L1	—	1.68	—	.066		
L2	—	1.78	—	.070		
L3	0.25 BSC		.010 BSC			

## NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
7. CONTROLLING DIMENSION: INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263CB.  
EXCEPT FOR DIMS. E, E1 & D1.

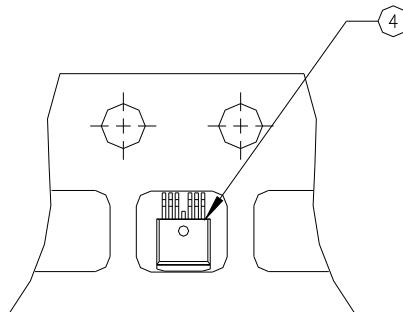
D<sup>2</sup>Pak - 7 Pin Part Marking Information

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

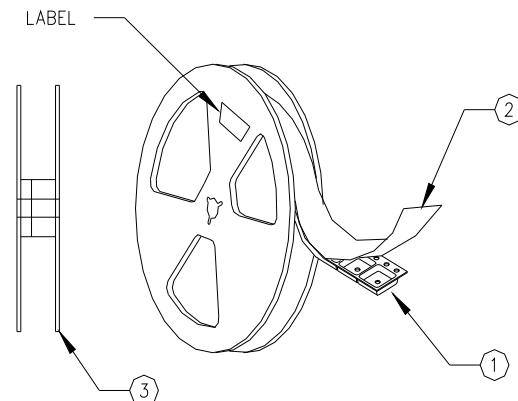
# D<sup>2</sup>Pak - 7 Pin Tape and Reel

## NOTES, TAPE & REEL, LABELLING:

1. TAPE AND REEL.
  - 1.1 REEL SIZE 13 INCH DIAMETER.
  - 1.2 EACH REEL CONTAINING 800 DEVICES.
  - 1.3 THERE SHALL BE A MINIMUM OF 42 SEALED POCKETS CONTAINED IN THE LEADER AND A MINIMUM OF 15 SEALED POCKETS IN THE TRAILER.
  - 1.4 PEEL STRENGTH MUST CONFORM TO THE SPEC. NO. 71-9667.
  - 1.5 PART ORIENTATION SHALL BE AS SHOWN BELOW.
  - 1.6 REEL MAY CONTAIN A MAXIMUM OF TWO UNIQUE LOT CODE/DATE CODE COMBINATIONS.  
REWORKED REELS MAY CONTAIN A MAXIMUM OF THREE UNIQUE LOT CODE/DATE CODE COMBINATIONS.  
HOWEVER, THE LOT CODES AND DATE CODES WITH THEIR RESPECTIVE QUANTITIES SHALL APPEAR ON THE BAR CODE LABEL FOR THE AFFECTED REEL.



2. LABELLING (REEL AND SHIPPING BAG).
  - 2.1 CUST. PART NUMBER (BAR CODE): IRFXXXXSTRL-7P
  - 2.2 CUST. PART NUMBER (TEXT CODE): IRFXXXXSTRL-7P
  - 2.3 I.R. PART NUMBER: IRFXXXXSTRL-7P
  - 2.4 QUANTITY:
  - 2.5 VENDOR CODE: IR
  - 2.6 LOT CODE:
  - 2.7 DATE CODE:



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

## Qualification Information

<b>Qualification Level</b>		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. Infineon's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
<b>Moisture Sensitivity Level</b>		D <sup>2</sup> -Pak 7 Pin	MSL1
<b>ESD</b>	Machine Model	Class M4 (+/- 800V) <sup>†</sup> AEC-Q101-002	
	Human Body Model	Class H3A (+/- 6000V) <sup>†</sup> AEC-Q101-001	
	Charged Device Model	Class C5 (+/- 2000V) <sup>†</sup> AEC-Q101-005	
<b>RoHS Compliant</b>		Yes	

<sup>†</sup> Highest passing voltage.

## Revision History

Date	Comments
4/2/2014	<ul style="list-style-type: none"> <li>Added "Logic Level Gate Drive" bullet in the features section on page 1</li> <li>Updated part marking on page 8</li> <li>Updated typo on the fig.19 and fig.20, unit of y-axis from "A" to "nC" on page 6.</li> <li>Updated data sheet with new IR corporate template</li> </ul>
11/4/2015	<ul style="list-style-type: none"> <li>Updated datasheet with corporate template</li> <li>Corrected ordering table on page 1.</li> </ul>

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